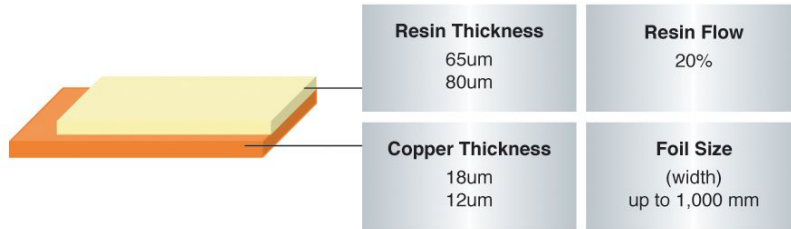


## DSF-400, DSF-400G, DSF-500

### BUILD-UP BOARD MATERIAL

Insulating material coated with partially cured resin onto the copper foil, can be used as a cap layer of MLB



### Features

- Glass-free
- Good laser processibility
- Low Dk, high operating speed
- Compatible with conventional lamination process
- Easier to produce finer line and space

### Applications

- Microvia formation for high density board
- Packaging solution for thinner, lighter product

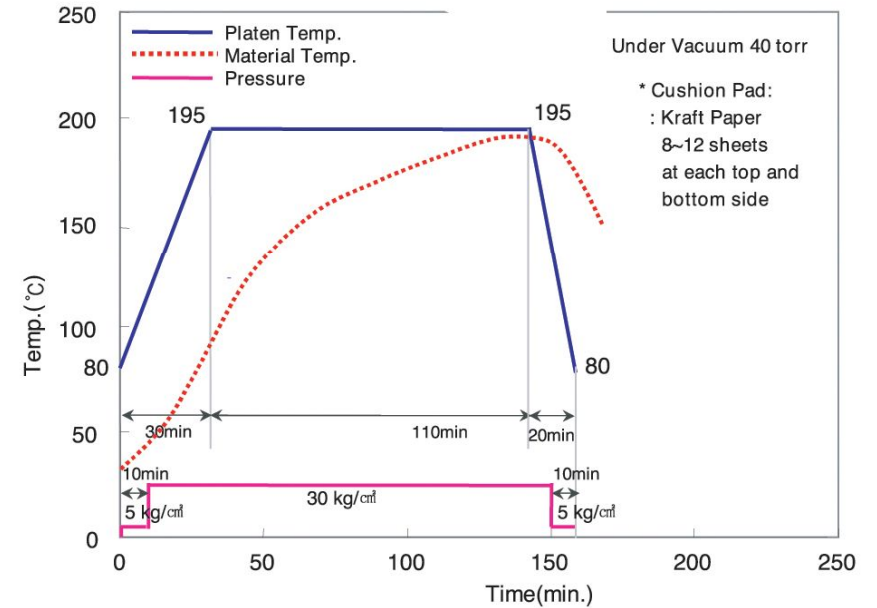
### General Properties

Test Item	Unit	Condition	DSF-400	DSF-400G	DSF-500
Flame Class	-	A	UL 94V-0	UL 94V-0	UL 94V-0
Tg (DMA)	°C	-	145	145	185
Insulation Resistance	ohm	C-96/20/65	$5 \times 10^{13} \sim 5 \times 10^{14}$	$5 \times 10^{13} \sim 5 \times 10^{14}$	$5 \times 10^{13} \sim 5 \times 10^{14}$
		C-96/20/65 + D-3/100	$5 \times 10^{12} \sim 5 \times 10^{13}$	$5 \times 10^{12} \sim 5 \times 10^{13}$	$5 \times 10^{12} \sim 5 \times 10^{13}$
Volume Resistivity	ohm-cm	C-96/20/65	$1 \times 10^{14} \sim 1 \times 10^{15}$	$1 \times 10^{14} \sim 1 \times 10^{15}$	$1 \times 10^{14} \sim 1 \times 10^{15}$
		C-96/20/65 + C-96/50/90	$5 \times 10^{13} \sim 5 \times 10^{14}$	$5 \times 10^{13} \sim 5 \times 10^{14}$	$5 \times 10^{13} \sim 5 \times 10^{14}$
Surface Resistance	ohm	C-96/20/65	$1 \times 10^{13} \sim 1 \times 10^{14}$	$1 \times 10^{13} \sim 1 \times 10^{14}$	$1 \times 10^{13} \sim 1 \times 10^{14}$
		C-96/20/65 + C-96/50/90	$5 \times 10^{12} \sim 5 \times 10^{13}$	$5 \times 10^{12} \sim 5 \times 10^{13}$	$5 \times 10^{12} \sim 5 \times 10^{13}$
Dielectric Constant (1GHz)		C-96/20/65	3.35	3.30	3.40
Dissipation Factor (1GHz)		C-96/20/65	0.025	0.025	0.025
Solder Float		288°C, 60 sec	good	good	good
		288°C, 60 sec	good	good	good
Peel Strength (H oz)	kgf/cm	A	1.4~1.6	1.2~1.4	1.4~1.6
		After Solder (260°C, 20 sec)	1.4~1.6	1.2~1.4	1.4~1.6
Specific Gravity		-	1.3~1.4	1.3~1.4	1.3~1.4

## DSF-400, DSF-400G, DSF-500

### BUILD-UP BOARD MATERIAL

### Recommended Press Cycle



- Material heating rate (80~130°C) : 1.8 ~ 2.2 °C/min
- Curing condition : above 165°C 80min~